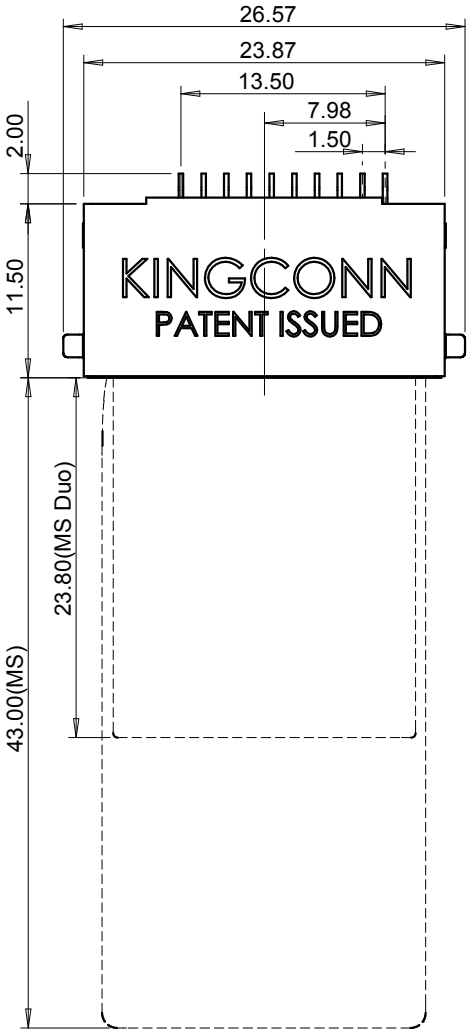
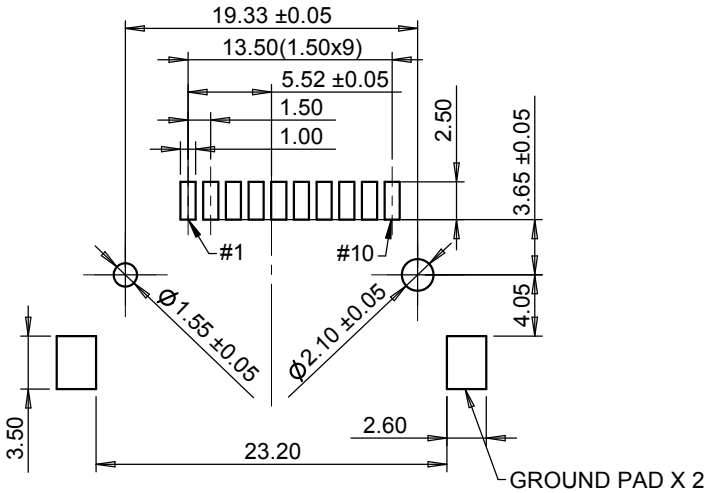
更改 REV	設 變 內 容 MODIFICATION
E	ECR00780
F	ECN00868





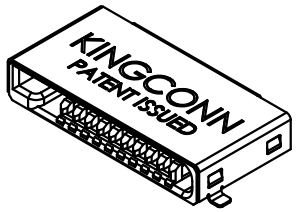
RECOMMEND PCB LAYOUT

NOTES :
1. MATERIAL :
   INSULATOR : HIGH TEMPRATURE THERMOPLASTIC, UL 94V-0, IVORY
   CONTACT : COPPER ALLOY
2. PART NO : MSMS-XX-X011

PACKING:
0:TRAY
1:CARRIER

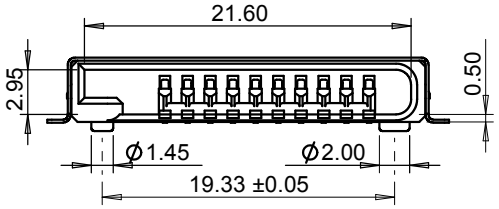
COLOR:
0:BLACK
9:IVORY

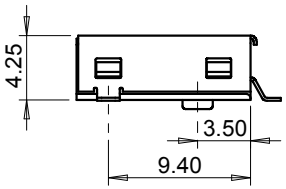
PANTING
F CONTACT:GOLD FLASH OVER 50u"MIN.NICKEL
SOLDER TAIL:100u"MIN.Sn OVER 50u"NICKEL
B CONTACT:10u"MIN.Au OVER 50u"MIN.NICKEL
SOLDER TAIL:100u"MIN.Sn OVER NICKEL



PIN DEFINITION

MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS





GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°

KINGCONN 皇海科技股份有限公司

名 稱(TITLE) MemoryStick & MemoryStick Duo Connector Normal type

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	MSMS-XX-X011	MSMS-XX-X011-F

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:1	張 數 SHEET 1/1
			角 法 PROJ.	更 改 REV F

QP-701-03